This presentation may contain forward-looking statements about MoSys, Inc. including, without limitation, benefits and performance expected from use of its embedded memory and interface technologies and ICs, improving operational efficiencies, the timing of product development and shipments of Bandwidth Engine® ICs, LineSpeed™ ICs, and line cards, anticipated benefits and performance expected from the Bandwidth Engine and LineSpeed products, and line cards, growth in the size of the market addressed by the Company’s business and the Company’s future markets and future business prospects. Forward-looking statements are based on certain assumptions and expectations of future events that are subject to risks and uncertainties. Actual results and trends may differ materially from historical results or those projected in any such forward-looking statements depending on a variety of factors. These factors include, but are not limited to the following:

- achieving additional design wins for our ICs;
- the timing of customer orders and product shipments;
- commencing volume shipments of ICs;
- our ability to enhance our existing proprietary technologies and develop new technologies;
- achieving necessary acceptance of our IC architecture and interface protocols by potential customers and their suppliers;
- difficulties and delays in the development, production, testing and marketing of our ICs;
- reliance on our manufacturing partners to assist successfully with the fabrication of our ICs;
- availability of quantities of ICs supplied by our manufacturing partners at a competitive cost;
- our lack of recent experience as a fabless semiconductor company making and selling proprietary ICs;
- level of intellectual property protection provided by our patents, the expenses and other consequences of litigation, including intellectual property infringement litigation, to which we may be or may become a party from time to time;
- vigor and growth of markets served by our licensees and customers and our operations; and

other risks identified in MoSys’ most recent reports on form 10-K and form 10-Q filed with the Securities and Exchange Commission, as well as other reports that MoSys files from time to time with the Securities and Exchange Commission. MoSys undertakes no obligation to update publicly any forward-looking statement for any reason, except as required by law, even as new information becomes available or other events occur in the future.
Overview

Fabless semiconductor company enabling carrier, data center and enterprise OEMs to meet ever-increasing demand for intelligent bandwidth and faster data throughput

IC Product Families Enable Cloud Infrastructure Equipment

- **Bandwidth Engine® ICs** - BE-1, 2, 3*: Highest memory access rate and intelligent offload for packet processing acceleration
- **LineSpeed™ PHYs** - Gearbox, Retimer, CDR: High-performance PHYs for throughput and density

Target Market

- Networking and Cloud Hardware OEMs
- Sweet Spot: Carrier Ethernet, core, edge and data center

Customers

- 85+ BE and LineSpeed design wins with 25+ customers
- Wins in 40Gb to 1Tb line cards and systems in routers, Metro Ethernet, wireless aggregation, optical systems, data center switches, security, load balancing, monitoring, broadcast video

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Led by an Experienced Team

Len Perham
CEO

40+ Yrs Experience
- CEO of IDT, Incubated MoSys
- Former Chairman of NetLogic (acquired by Broadcom; exit >$3B)
- Zilog, AMD, Western Digital

Michael Miller
VP Sys. Applications

30+ Yrs Experience
- CTO IDT
- Over 25 Patents, including JTAG
- Architected QDR, ZBT, TCAMs

Tom Riordan
COO, EVP Engineering

30+ Yrs Experience
- CEO Exclara
- VP PMC-Sierra
- Founder & CEO, QED
- MIPS, Intel

Jim Sullivan
CFO

25+ Yrs Experience
- CFO Apptera
- CFO 8x8
- CFO Netergy Microelectronics

John Monson
VP Sales & Marketing

25+ Yrs Experience
- VP Mktg Mellanox
- VP Inphi & Scintera Networks
- VP Mktg PMC-Sierra
- AT&T, Lucent

Mikhal Miller
VP Sys. Applications

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COO, EVP Engineering

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CFO

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- CFO Netergy Microelectronics

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Fast, Intelligent and Secure Cloud Network

*Leads to New System Bottlenecks*

Network Speed & Traffic Increasing

Cloud Services Need Intelligent & Secure Networks

Both Requirements Create New

**Throughput & Memory Bandwidth Bottlenecks**

for Network Equipment Manufacturers

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Combination of Throughput and Intelligence Creates Bottlenecks

Typical Networking Line Card

Bottlenecks:

- **Data Throughput**
  - Power / Distance
  - Signal Integrity
  - Rate Adaptors

- **Memory Access**
  - Bandwidth
  - Pins
  - Power
  - Area
Data Path & Memory Bandwidth ICs
Solve Bottlenecks when Aggregate Data Throughput >100Gb/s

Serial Offers Higher Performance with Reduced Area, Pin Count, Power and Cost

Datapath Solutions

Optics Modules

MoSys LineSpeed Gearbox or Retimer

MoSys LineSpeed CDR

Data from Network

Typical Networking Line Card

MAC/ Framers
FPGA/ASSP

Packet Processing Engine/Switch
FPGA / NPU

Bandwidth Engine

Memory Access Solutions

DDR

Backplane
10G ➔ 25G per lane

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Market is Expanding as 100G+ Spreads
Target Customers Throughout Network & Data Center

New Markets for 100G:
- Modules
- Government
- Video

Access
- Cisco
- Hitachi
- Fujitsu
- H3C
- Ericsson
- Others

Aggregation
- Cisco
- Juniper
- ALU
- Huawei
- ZTE

Core
- Cisco
- ALU
- Ciena
- Fujitsu
- Huawei
- Ericsson

Data Center

DC Edge
- Palo Alto
- F5
- Huawei/Sym
- Others

Ent/DC Switch
- Cisco
- Brocade
- HP/H3C
- Arista

Optical/Copper Module
- Finisar
- JDSU
- Sumitomo

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Established FPGA Ecosystem
Simplifies Implementation for New BE-2 and BE-3 Designs

- Proven Platforms and Ecosystem with Xilinx and Altera/Intel FPGAs

Altera Stratix IV, Stratix V, Arria 10

Xilinx Virtex-6, Virtex-7, UltraScale

MoSys BE-2 and BE-3 FPGA Evaluation Platforms

MoSys Provides Reference Designs to Speed Customer Design Process

- Memory Controller & App Functions
- GCI PCS / Framer

Bandwidth Engine® IC
- 1T-SRAM
- ALU
- Macro Functions
- Bit Safe Technology

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**Broadening FPGA Application Examples**

*Bandwidth Engine Wins on Performance, Size, Pins, Power, Cost*

---

**Edge Router**

400G Oversubscription

*Traffic smoothing prevents dropped packets*

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**Data Center Security**

Security Acceleration

*Threat Prevention – multiple lookup and buffering functions*

---

**Advantages vs. Alternatives**

- Memory access performance
- Lower - pin count, area, power, cost

---

Memory access performance

- RLDRAM won’t fit or route
Leading EZchip / Mellanox Network Processor
Leverages Bandwidth Engine 3 for Performance and Features

- Collaboration with EZchip NPS-400
- Industry-leading merchant NPU integrated MoSys BE-3 interface
- 50% Increase in Memory Bandwidth

- Leverage existing EZchip market presence in carrier Ethernet
- Mellanox acquisition strengthens access to Data Center / Edge
LineSpeed PHY Products
Flexible Features, Signal Integrity, Power and Density

Supports Low Power 10, 25, 40, and 100G Interfaces

100G CFP and QSFP28 Module Applications

- Single Chip
- Small Size
- Performance
- Ease of Use

100G to 1Terabit Line Card Applications

Source: Company Management

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Product Trends Indicative of Future Growth

- **Barriers to Adoption Reduced**
  - Serial Technology Proven
  - Industry-Leading Partners
    - Xilinx, EZchip/Mellanox, Altera/Intel
  - BE Dual Sourcing Relationship
    - GSI Technology

- **Long life cycle for Products**

- **Design Win Momentum**
  - 85 Wins (cumulative)
  - 25+ Customers
  - Customer Re-use

- **Adding Synergistic Products**
  - Bandwidth Engine 3 family
  - LineSpeed Flex 28nm PHY family
Expanding Market Opportunity for High Throughput Designs

<table>
<thead>
<tr>
<th>Line Cards (LC)/System</th>
<th>Access</th>
<th>Aggregation</th>
<th>Core</th>
<th>Data Center / Edge</th>
</tr>
</thead>
<tbody>
<tr>
<td>1-4</td>
<td>4-10</td>
<td>4-16</td>
<td>4-16</td>
<td></td>
</tr>
<tr>
<td>Bandwidth Engine/LC</td>
<td>1-2</td>
<td></td>
<td>Up to 10+</td>
<td>4-16</td>
</tr>
<tr>
<td>LineSpeed/LC</td>
<td>1-2</td>
<td>4-10</td>
<td>Up to 10</td>
<td>4-10</td>
</tr>
<tr>
<td>IC Per Interface Module</td>
<td>1</td>
<td></td>
<td>1-4 per module, 1-10 modules per LC</td>
<td></td>
</tr>
</tbody>
</table>
Opportunity Growth
Driven by Increased Network Capacity & New Applications

Estimate Growing Accessible market >$500M

Market definition and other information is based on management opinion.
Increasing Revenue Potential
Based on Design Win Trends & New Products

Strong Revenue Potential
24 mos Design-to-Production
Design Qualification
Field Trial / Verification
Production life approx. 5-10 yrs

Increasing Design Win Base
Design Wins by year

2012 Design-to-Production
2013 Design-to-Production
2014 Design-to-Production
2015 Design-to-Production

Potential 2012 DW Production Revenue

2015 Revenue based on 2013 DW

2016 Revenue based on 2014 DW

2017 Revenue based on 2015 DW

Increasing Revenue Potential

2012 Design-to-Production
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2015 Revenue based on 2013 DW

2016 Revenue based on 2014 DW

2017 Revenue based on 2015 DW

Potential 2012 DW Production Revenue
## Target Operating Model

<table>
<thead>
<tr>
<th>Targets</th>
<th>Medium Term</th>
<th>Long Term</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Revenue Growth (YoY)</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>• 2016 IC Revenue Est: $7-9M</td>
<td>100%+ YoY</td>
<td>40%+ YoY</td>
</tr>
<tr>
<td>• Up from $2.4M in 2015</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• 85 total Design Wins: BE2 &gt;70%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• LT strengthened by BE3 and LS Flex</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Gross Margin</strong>*</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• Improvements from volume efficiency</td>
<td>50%</td>
<td>60%+</td>
</tr>
<tr>
<td>• Analog products</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• BE2 mask optimization</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Operating Margin</strong>*</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• 1Q16 reduced Opex ~$4-5M annually</td>
<td>NA</td>
<td>20%+</td>
</tr>
<tr>
<td>• Non-GAAP Opex ~$5M / qtr (exclude tape outs)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• Break-even level ~$10M IC Revenue per quarter</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Cash Flow</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>• $20M cash @ 12/31/15</td>
<td>Declining Cash Burn</td>
<td>Cash - Generating</td>
</tr>
<tr>
<td>• Need additional capital to achieve break-even</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

*Non-GAAP measures that exclude stock-based compensation expenses and amortization of intangibles*
## Summary Income Statement (Non-GAAP*)

*Non-GAAP: Excludes non-cash charges: stock-based compensation and amortization of intangibles*

### In Millions, except EPS

<table>
<thead>
<tr>
<th></th>
<th>2015</th>
<th>Q4 15</th>
<th>Q3 15</th>
<th>Q2 15</th>
<th>Q1 15</th>
<th>2014</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Total Revenues</strong></td>
<td>$ 4.4</td>
<td>$ 1.6</td>
<td>$ 1.1</td>
<td>$ 1.0</td>
<td>$ 0.8</td>
<td>$ 5.4</td>
</tr>
<tr>
<td><strong>Product</strong></td>
<td>2.4</td>
<td>1.1</td>
<td>0.6</td>
<td>0.5</td>
<td>0.2</td>
<td>2.3</td>
</tr>
<tr>
<td><strong>Royalty and other</strong></td>
<td>2.0</td>
<td>0.5</td>
<td>0.5</td>
<td>0.5</td>
<td>0.6</td>
<td>3.1</td>
</tr>
<tr>
<td><strong>Gross Profit</strong></td>
<td>1.9</td>
<td>0.7</td>
<td>0.2</td>
<td>0.4</td>
<td>0.5</td>
<td>3.1</td>
</tr>
<tr>
<td><strong>Margin %</strong></td>
<td>44%</td>
<td>45%</td>
<td>22%</td>
<td>43%</td>
<td>69%</td>
<td>57%</td>
</tr>
<tr>
<td><strong>R&amp;D</strong></td>
<td>24.1</td>
<td>5.0</td>
<td>8.2</td>
<td>5.2</td>
<td>5.7</td>
<td>24.8</td>
</tr>
<tr>
<td><strong>SG&amp;A</strong></td>
<td>5.3</td>
<td>1.4</td>
<td>1.3</td>
<td>1.3</td>
<td>1.3</td>
<td>5.4</td>
</tr>
<tr>
<td><strong>Total Op Ex</strong></td>
<td>29.4</td>
<td>6.4</td>
<td>9.5</td>
<td>6.5</td>
<td>7.0</td>
<td>30.2</td>
</tr>
<tr>
<td><strong>Net Loss</strong></td>
<td>$(27.5)</td>
<td>$(5.7)</td>
<td>$(9.3)</td>
<td>$(6.1)</td>
<td>$(6.5)</td>
<td>$(27.1)</td>
</tr>
<tr>
<td><strong>EPS</strong></td>
<td>$(0.44)</td>
<td>$(0.09)</td>
<td>$(0.14)</td>
<td>$(0.09)</td>
<td>$(0.12)</td>
<td>$(0.55)</td>
</tr>
</tbody>
</table>
Balance Sheet

<table>
<thead>
<tr>
<th></th>
<th>Q4 – December 31, 2015 (in millions)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash &amp; Investments</td>
<td>$20.2</td>
</tr>
<tr>
<td>Total Assets</td>
<td>$40.7</td>
</tr>
<tr>
<td>Debt</td>
<td>-</td>
</tr>
<tr>
<td>Total Liabilities</td>
<td>$3.9</td>
</tr>
<tr>
<td>Stockholder’s Equity</td>
<td>$44.8</td>
</tr>
<tr>
<td>Total Shares Outstanding</td>
<td>65.5</td>
</tr>
</tbody>
</table>
Investment Highlights

- IC Products Solve Key Networking & Cloud Challenges
- Differentiated Products with Long Lifetime
- Market Trends & Partnerships Pave Way for Future Success
- Dedicated Organization, Proven Veteran Leadership
Thank You

Contact Information:  
Jim Sullivan, MoSys, Inc.  
Chief Financial Officer  
408-418-7582  
jsullivan@mosys.com  

Beverly Twing, Shelton Group  
Investor Relations  
214-272-0089  
btwing@sheltonigroup.com